

Page 15 line 24 word 1 is amended to read "which may be adhesive, photoresist, BCB, and/or polyimide, bringing".

This amendment is believed to introduce no new matter as epoxy and adhesive can be used interchangeably, and

5 photoresist, BCB, and polyimide have been used for wafer bonding in prior art.

In the drawings

10 The label of FIG. 12 is amended to read FIG. 12a; FIG. 12b and FIG. 12c are added. The two added figures (12b and 12c) were inadvertently omitted during drafting. They were mentioned in both the **Brief Description of Drawings** in page 13, lines 8 through 16, and **Detailed Description of**
15 **Drawings** in page 31 line 29. In addition, FIG. 13a, and FIG. 13b were drafted inaccurately, and are amended.

Please find the amended **replacement sheet** 1 and 2 in the next two pages (10 and 11).